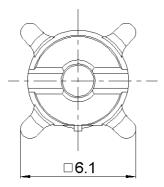
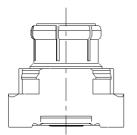
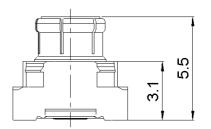
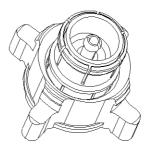
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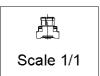
Series: MMBX











All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	BRONZE,BRASS BERYLLIUM COPPER; BRASS - PTFE	NPGR NPGR
:	-	-

Issue: 0808 B

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



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Series: MMBX

PACKAGING

SPECIFICATION

Standard	Unit	Other
100	'W' option Contact us	

ELECTRICAL CHARACTERISTICS

ENVIRONMENTAL

Impedance 50Ω

Frequency 0-12.4 GHz

VSWR 1.065 + 0,0000 x F(GHz) Maxi

Insertion loss $0.12 \ \sqrt{F(GHz)} \ dB \ Maxi$ RF leakage - ($100 \ - F(GHz)) \ dB \ Maxi$

Voltage rating 330 Veff Maxi Dielectric withstanding voltage Insulation resistance 1000 Veff mini 1000 M Ω mini

Operating temperature -55/+155 ° C Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHER CHARACTERISTICS

Assembly instruction

Others:

to 2GHz (1.106 --- 2 to 6GHz) Interface MMBX only ,up to 2.5GHz PCB to PCB -45 dB up to 2.5 GHz

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

10 N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 100 Cycles mini

Weight **0,4200** g

Issue: 0808 B

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Series: MMBX

- Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.

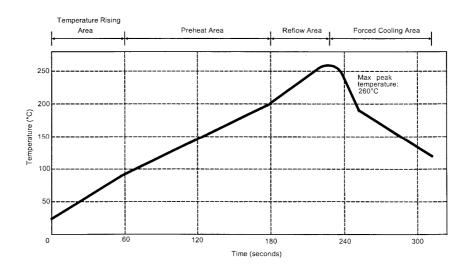
Adhesive agents must not be used on the receptacle.

This process of soldering has been tested with convection oven. Below please find, the typical profile to use.

A video camera is recommended for positioning of the component.

- The cleaning of printed circuit boards is not obliged.
- Verification of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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necessary.

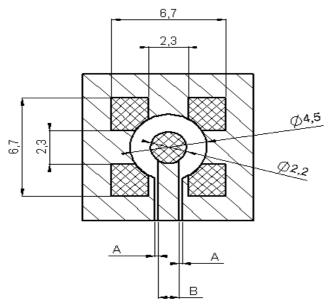


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Series: MMBX

MMBX SERIES INFORMATIONS

PCB



COPLANAR LINE

Pattern and signal are on the same side The material of PCB is epoxy resin (FR4). (Er = 4.6)

The solder resist should be printed Except for the land pattern on the PCB



Pattern



APPLICATION 75Ω

WITH B = 0.55mm

PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,350
1,0	0,360
1,2	0,365
1,6	0,375

APPLICATION 50Ω

WITH B = 1,2mm

PCB thickness (mm)	Coplanar ligne A (mm)	
0,8	0,190	
1,0	0,200	
1,2	0,205	
16	0.210	

Issue: 0808 B

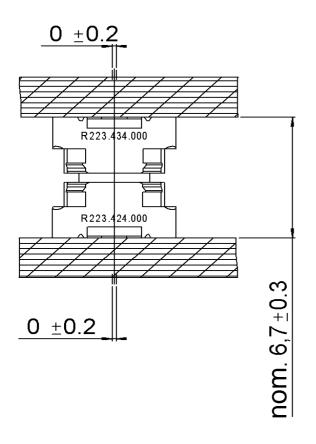
In the effort to improve our products, we reserve the right to make changes judged to be

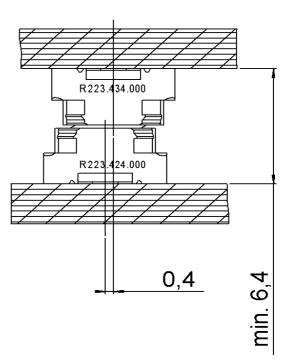


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Series: MMBX

MMBX SERIES INFORMATIONS





Issue: 0808 B

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